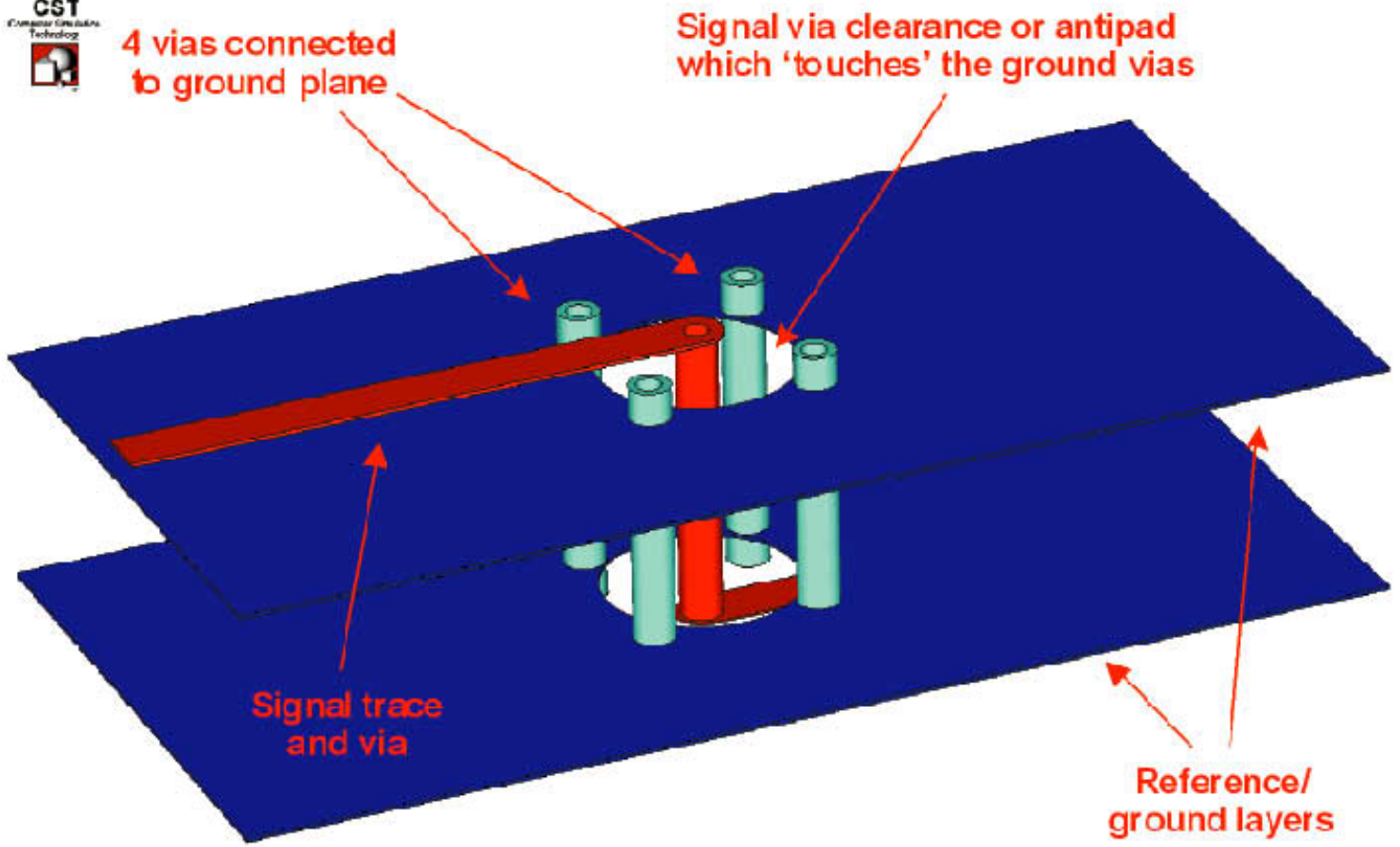


Figure 1



New techniques for pc-board-layer-interconnect design provide predictable path impedance and improved signal integrity.